

563ZXC-6A

Description

• Size: 5mm (T1-3/4) round package.

• Emitting color: Ultra pure green.

Main Features

- Instant light less than 100ns turn on time.
- Superior resistance to moisture.
- Low drive current, recommend forward current: IF= 10- 20mA.

- Lens color: Water clear.
- Lead type: Radial leads.
 - Pb-Free.
 - Reliable and rugged.
 - Cool beam, safe to touch.

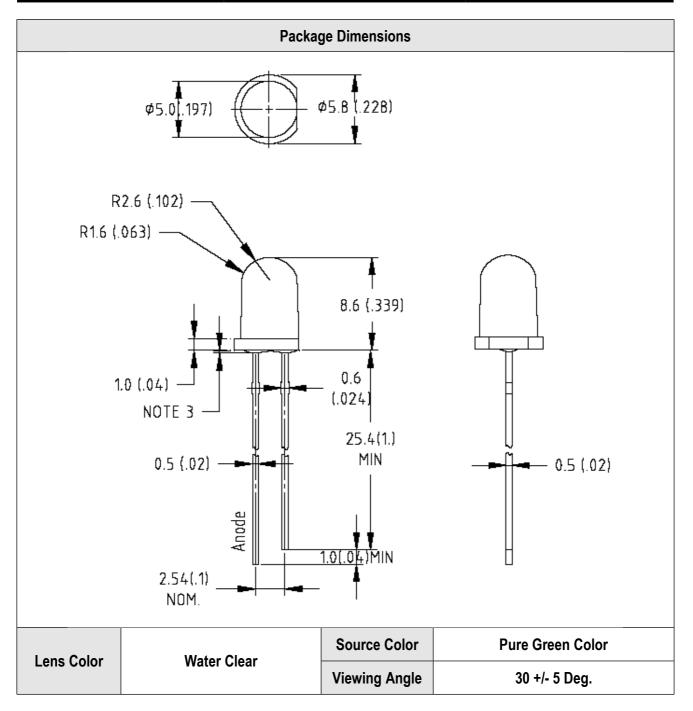
Absolute Maximum Rating TA=25°C									
Parameter	Symbol	Rating	Unit	Notice					
Power Dissipation	Pd	80	mW	IF = 20mA					
DC Forward Current	lF	20	mA						
Pulse Forward Current	IF (PEAK)	100	mA	Duty 1/10 @ 1KHz					
Derating Linear From 50°C		0.4	mA / °C						
Reverse Voltage	VR	5	V	Under 100uA					
Operating Temperature Range	T OPR	-30 to +80	°C						
Storage Temperature Range	T stg	-40 to +100	°C	Humidity should be under 50%					
Lead Soldering Temperature	T SOL	260 +/-5	°C	4mm (0.157") from mold body Les then 5 Second					

Part Selection Electrical / Optical Characteristics At TA-25°C									
Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit.			
Forward Voltage	VF	IF =20mA		3.20	3.80	V			
Reverse Current	lr	Vr =5V	—		50	uA			
Luminous Intensity (Note 1)	lv	IF =20mA	6500	14000		mcd			
Peak Emission Wavelength	λρ	IF =20mA	515	520	525	nm			
Spectral Line Half Width	Δλ	IF =20mA	45	50	55	nm			
Dominant Wavelength (Note 2)	λd	IF =20mA	520	525	530	nm			

Note 1: Luminous intensity is measured with a light sensor and filter combination that approximates the CIE eye-response curve.

Note 2 :The dominant wavelength (λ d) is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.

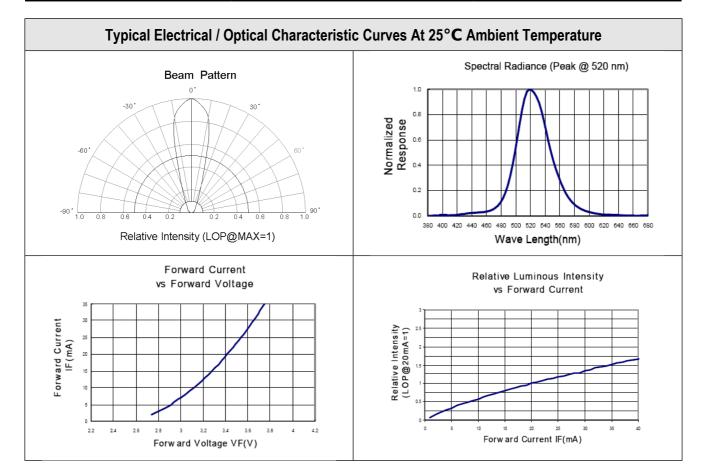




NOTES:

- All dimensions are in millimeters (inches).
- Tolerance is ±0.25 mm (.010") unless otherwise noted.
- Protruded resin under flange is 1.0mm(.04") max
- Lead spacing is measured where the leads emerge from the package.
- Specifications are subject to change without notice.





NOTE:

- θ_{1/2} is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- Clean only in isopropanol, ethanol, Freon TF (or equivalent).
- When using this product, Please observe the absolute maximum rating and the instructions for use outlined from use of the product, which does not comply with the absolute maximum rating and the instructions included in these specification sheet.

• Q.A Outgoing inspection standard:

Major Defect 0.65 A.Q.L. Minor Defect 1.5 A.Q.L

- Check at a distance of 30cm from the LED to the eye defects.
- Lead Forming:

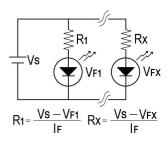
If forming is required, it must be done before soldering. Form pin leads by securing under 5mm from body and bedding with radio pliers or the equivalent to avoid pressure on resin. When the LED is mounted into a P.C.board, pitch spacing should be aligned to prevent cause any stress to the resin. Any unsuitable stress applied to resin may break bonding wire in LED, which will cause failure.

• Over-current-proof:

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

• Parallel connection:

Customer must apply series resistor in each LED under parallel connection. Otherwise VF difference will cause LED array lighting not even.





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Precautions For Use

Reverse voltage protection diode:

We recommend user put a reverse protective diode in parallel with LED, which is to prevent high reverse voltage caused the LED damage.

Recommend check all LED after assembled.

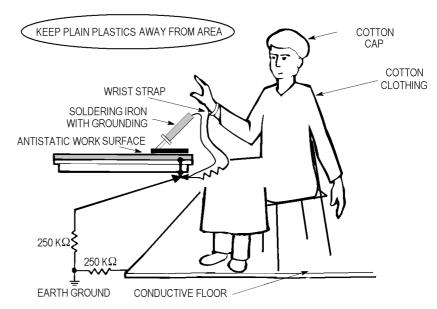
When inspecting the final products in which LED were assembled, it is recommended to check

whether the assembled LED are damaged by static electricity or not. It is easy to find static-damaged LED by a light-on test or VF test at a lower current (blow 1mA is recommended). Damaged LED will show some unusual characteristics such as the leak current remarkably increase, the forward voltage becomes lower or the LED do not light at the low current.

Criteria : (VF>2.0V at IF=0.5mA)

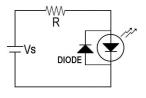
LED handling for ESD protection

- Keep all common plastics such as Styrofoam molded containers, packaging "popcorn balls", vinyl and teflon containers and plastic wrap away from LED components and PC board assemblies.
- Have all operators that handle LED components wear wrist ground straps, that are in fact touching their skin and securely grounded through a 250 K ohm resistor.
- Operators should wear only cotton clothing. Clothing made of synthetic fabrics, such as nylons, polyesters and acrylics, quickly build up a very lar



and acrylics, quickly build up a very large static charge with normal body movement.

- Use only tables and benches that are covered with ESD protective pads, having a surface insulation resistance of 1012 ohms per square. The high surface resistance permits the static charge to bleed off very slowly at an energy level sufficiently low enough to prevent any damage to an LED component.
- Ground all metal work bench frames and other equipment through a 250 k ohm current limiting resistor to prevent the rapid bleed-off of electric charge.
- Store LED components and PC board assemblies only in ESD protective packaging and use that packaging for transporting from one location to another. Plastic ESD protective containers are made from surfactant impregnated resins, such as polyethylene. The impregnated surfactants maintain a microscopic film of moisture on the surface of the plastic which prevents the build up of any static charge.
- Never apply adhesive tape or an adhesive label to a PC board assembly for temporary identification through the assembly process. The turboelectric charge that is created, when it is removed prior to shipment may damage the LED components.
- Continually train and remind operators and other personnel of the rules and procedures to be followed to protect LED





components and PC board assemblies from ESD damage.